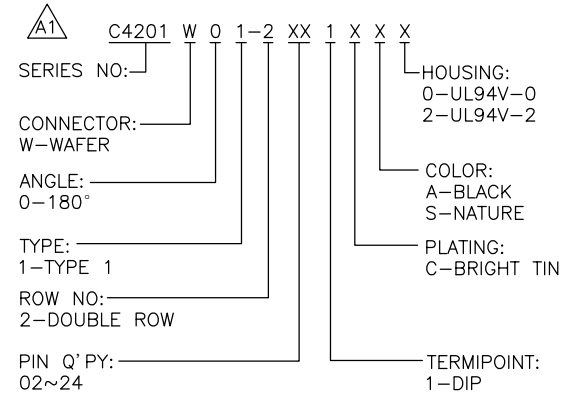


The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements



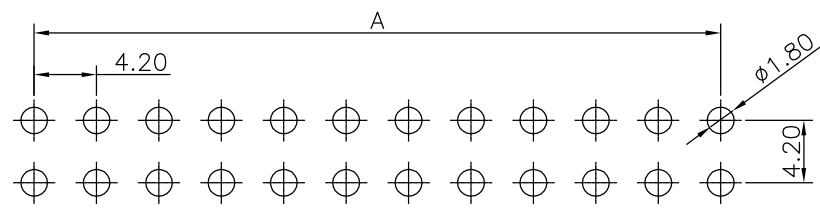
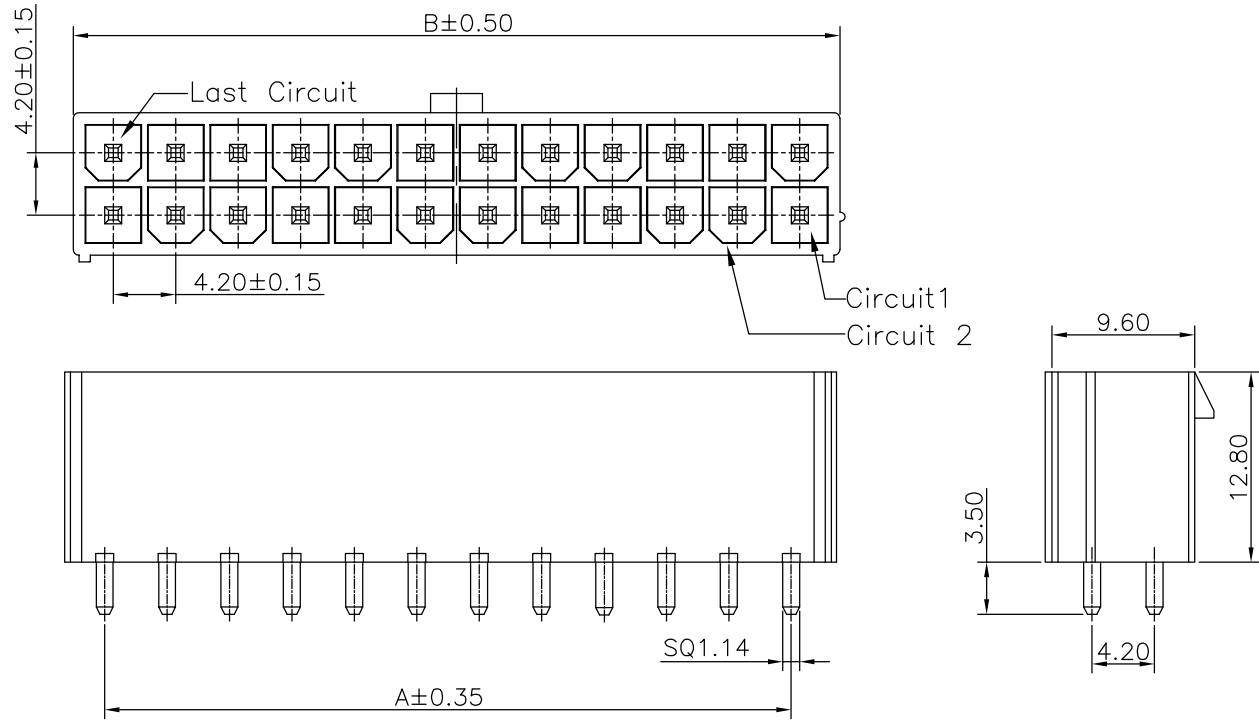
NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1-1.HOUSING: PA66
 - 1-2.CONTACTS: BRASS
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS: TIN/GOLD FLASH PLATED OVER ALL.
- 3.ELECTRICAL PERFORMANCE:
 - 3-1.CURRENT RATING: 9A
 - 3-2.CONTACT RESISTANCE: 10 mΩ MAX
 - 3-3.INSULATION RESISTANCE: 1000MΩ Min
 - 3-4.DIELECTRIC WITHSTANDING : 1500V
- 4.ENVIRONMENTAL PERFORMANCE:
 - 4-1.OPERATING TEMPERATURE: -25°C~+85°C.
- 5.PACKAGE SPEC: PE BAG
- 6.P/N:



Ordering Information & Dimensions

| Circuit | Dimensions (mm) | | Circuit | Dimensions (mm) | |
|---------|-----------------|-------|---------|-----------------|-------|
| | A | B | | A | B |
| 2*01 | --- | 5.40 | 2*07 | 25.20 | 30.60 |
| 2*02 | 4.20 | 9.60 | 2*08 | 29.40 | 34.80 |
| 2*03 | 8.40 | 13.80 | 2*09 | 33.60 | 39.00 |
| 2*04 | 12.60 | 18.00 | 2*10 | 37.80 | 43.20 |
| 2*05 | 16.80 | 22.20 | 2*11 | 42.00 | 47.40 |
| 2*06 | 21.00 | 26.40 | 2*12 | 46.20 | 51.60 |

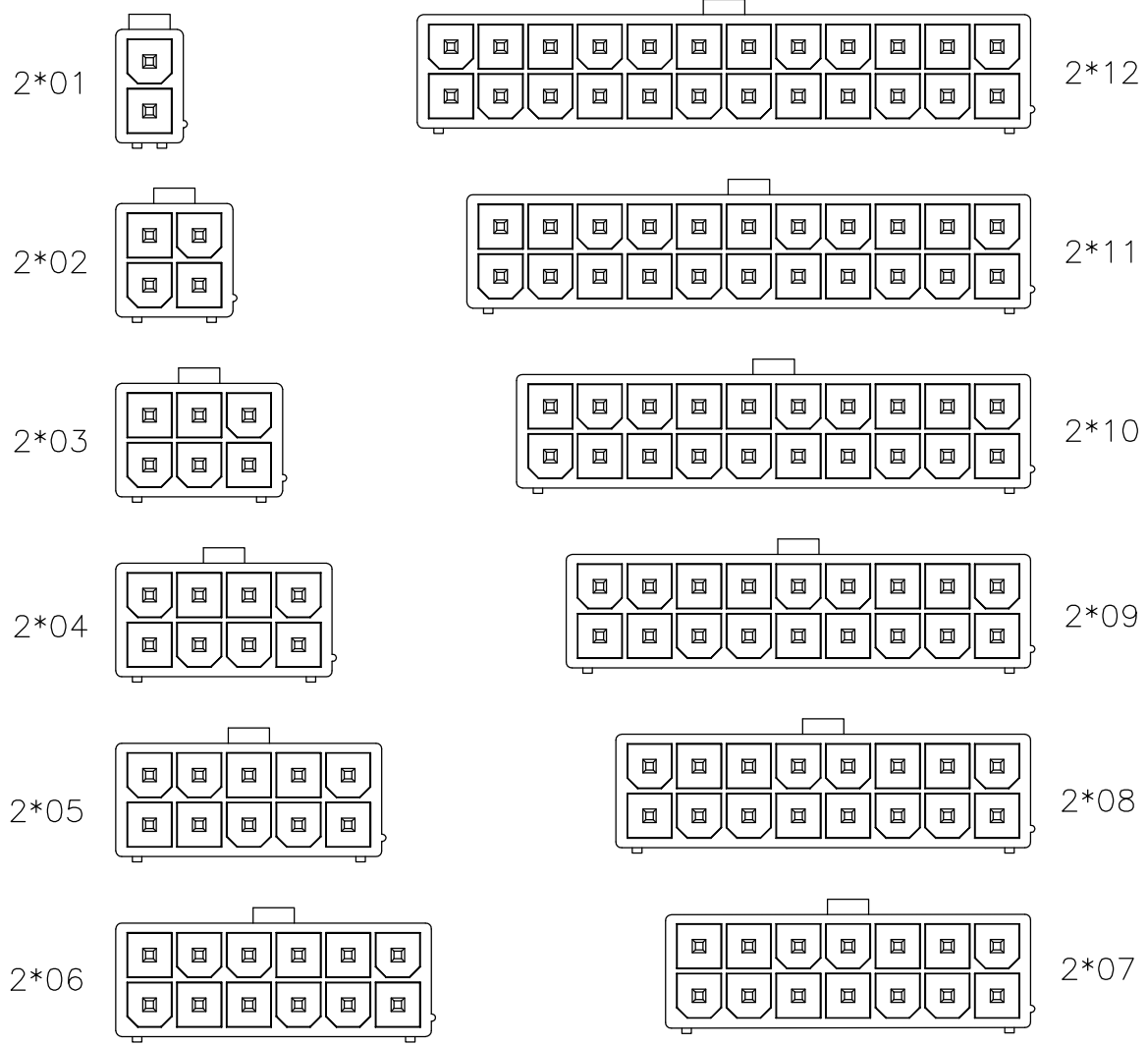


RECOMMENDED PCB LAYOUT
(GENERAL TOLERANCE:±0.05)

| REV. | REVISION RECORD | DATE | UNIT:mm | GENERAL TOLERANCES | | SCALE: | NAME | DATE | PART.NO: | DWG.NO: | |
|------|---------------------|----------|------------|--------------------|----------|---------|----------|----------|-----------------------------------|---------|------------|
| A0 | NEW RELEASE | 21.11.17 | | LINEAR | ANGLES | 1:1 | Wang_jr | 23.09.08 | C4201W01-2XX1XXX | ENDE05 | |
| A1 | PART NUMBER RENEWAL | 23.09.08 | 0.00±0.25 | X'±3' | DESIGNER | Han_Gao | 23.09.08 | TITLE: | Pitch 4.2mm 双排 180° DIP Wafer 实心针 | | REV: A1 |
| | | | 0.000±0.10 | X'X' ±2' | DRAWN | LX_HOU | 23.09.08 | | | | SHEET: 1/3 |

The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

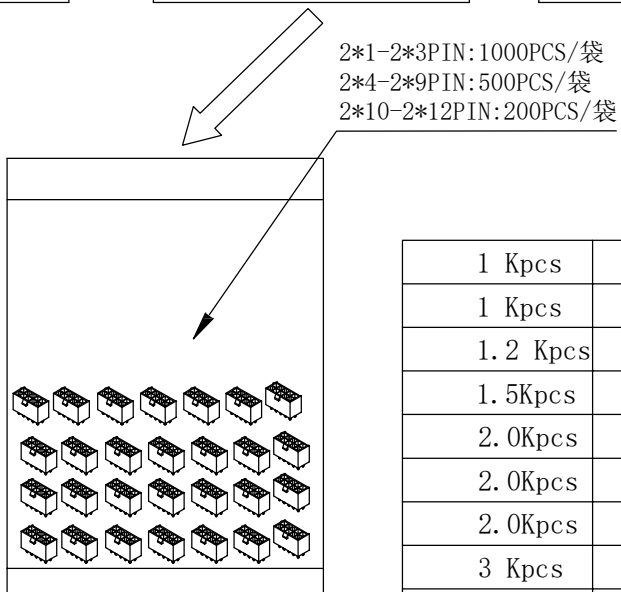
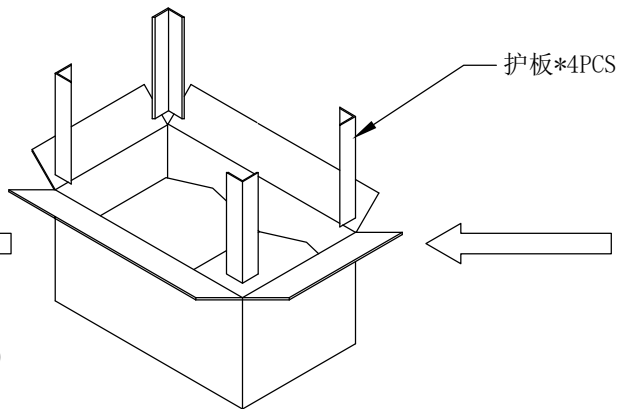
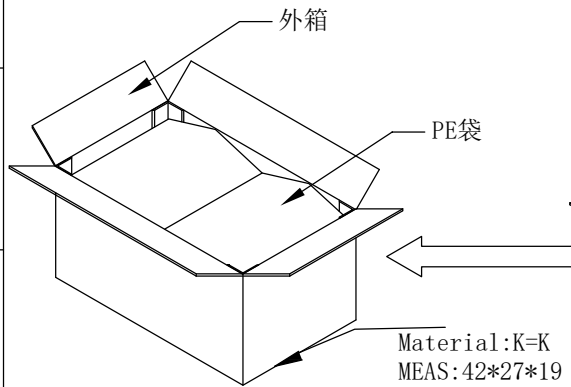
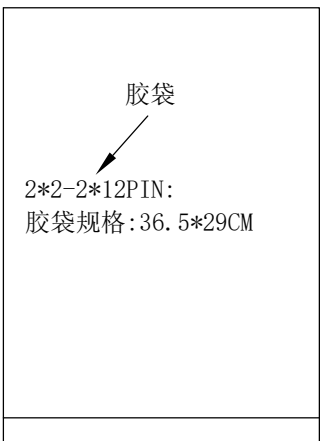
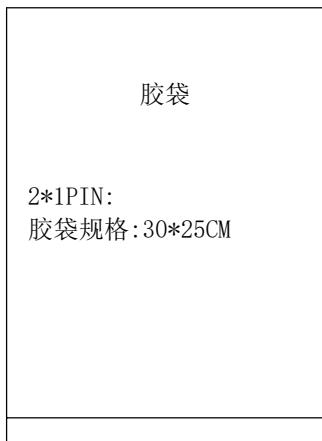
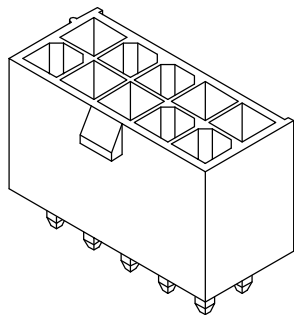
RoHS



| | | | | | | | | | | | |
|------|---------------------|----------|----------|--------------------|----------|---------------|---------|----------|-----------------------------------|-------------------|---------------------------------|
| REV. | REVISION RECORD | DATE | | GENERAL TOLERANCES | | SCALE: 1:1 | NAME | DATE | PART.NO: C4201W01-2XX1XXX | DWG.NO: ENDE05 | WanLian Technology Co., Ltd |
| A0 | NEW RELEASE | 21.11.17 | | LINEAR | ANGLES | APPROVED | Wang_jr | 23.09.08 | | | |
| A1 | PART NUMBER RENEWAL | 23.09.08 | UNIT:mm | 0.00±0.25 | X'±3' | DESIGNER | Han_Gao | 23.09.08 | TITLE: | | |
| | | | SIZE: A4 | 0.000±0.10 | X'X' ±2' | DRAWN | LX_HOU | 23.09.08 | Pitch 4.2mm 双排 180° DIP Wafer 实心针 | | |
| | | | | | | | | | | REV: A1 | SHEET: 2/3 |

The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS



| | | |
|-------------|---------|-------|
| 1 Kpcs | 0.2Kpcs | 2*12P |
| 1 Kpcs | 0.2Kpcs | 2*11P |
| 1.2 Kpcs | 0.2Kpcs | 2*10P |
| 1.5Kpcs | 0.5Kpcs | 2*9P |
| 2.0Kpcs | 0.5Kpcs | 2*8P |
| 2.0Kpcs | 0.5Kpcs | 2*7P |
| 2.0Kpcs | 0.5Kpcs | 2*6P |
| 3 Kpcs | 0.5Kpcs | 2*5P |
| 3.5Kpcs | 0.5Kpcs | 2*4P |
| 5 Kpcs | 1Kpcs | 2*3P |
| 8 Kpcs | 1Kpcs | 2*2P |
| 10 Kpcs | 1Kpcs | 2*1P |
| PCS/Cartion | PCS/Bag | POS |

注意事项:

- 1.袋装产品封口前需放1-2包干燥剂于内;
- 2.产品不可少数、多数;
- 3.内外包装均需有数量标签;
- 4.不同PIN位包装时须分开放置不可装入同一外箱中。
- 5.尾数包装需用不影响品质之物品填充并注明尾数。

| REV. | REVISION RECORD | DATE | | GENERAL TOLERANCES | | SCALE: 1:1 | NAME | DATE | PART.NO: | DWG.NO: | WanLian Technology Co., Ltd |
|------|---------------------|----------|----------|--------------------|----------|---------------|----------|----------|------------------|---------|---------------------------------|
| A0 | NEW RELEASE | 21.11.17 | | LINEAR | ANGLES | APPROVED | Wang_jr | 23.09.08 | C4201W01-2XX1XXX | ENDE05 | |
| A1 | PART NUMBER RENEWAL | 23.09.08 | UNIT:mm | X'±3' | DESIGNER | Han_Gao | 23.09.08 | TITLE: | | | |
| | | | SIZE: A4 | X'X' ±2' | DRAWN | LX_HOU | 23.09.08 | 包装图 | | | |

REV: A1 SHEET: 3/3